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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	68 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c711t-04i-so

4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C71X family has a 13-bit program counter capable of addressing an 8K x 14 program memory space. The amount of program memory available to each device is listed below:

Device	Program Memory	Address Range
PIC16C710	512 x 14	0000h-01FFh
PIC16C71	1K x 14	0000h-03FFh
PIC16C711	1K x 14	0000h-03FFh
PIC16C715	2K x 14	0000h-07FFh

For those devices with less than 8K program memory, accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PIC16C710 PROGRAM MEMORY MAP AND STACK

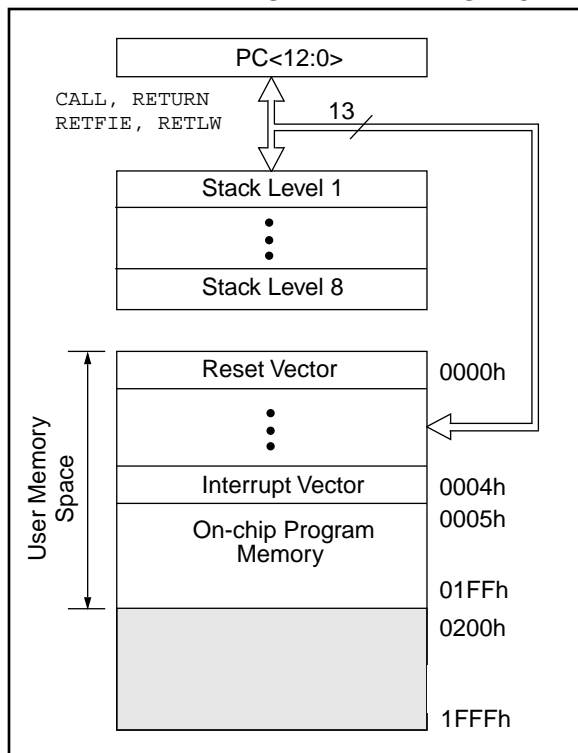


FIGURE 4-2: PIC16C71/711 PROGRAM MEMORY MAP AND STACK

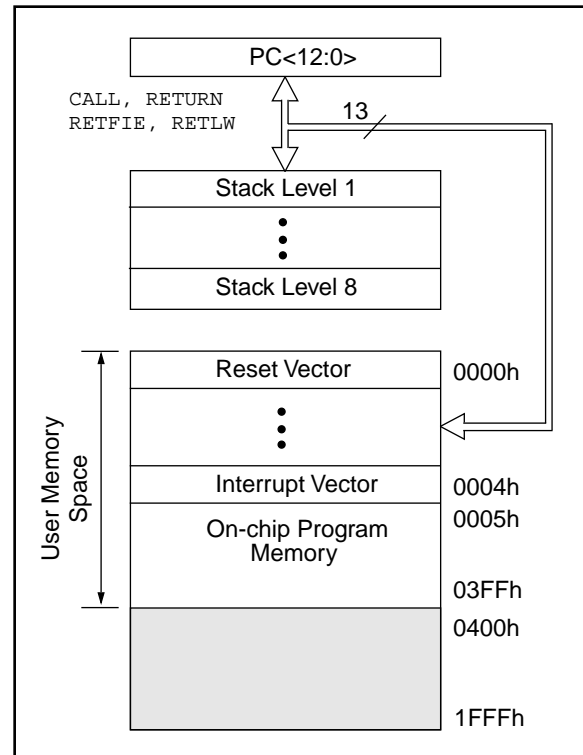
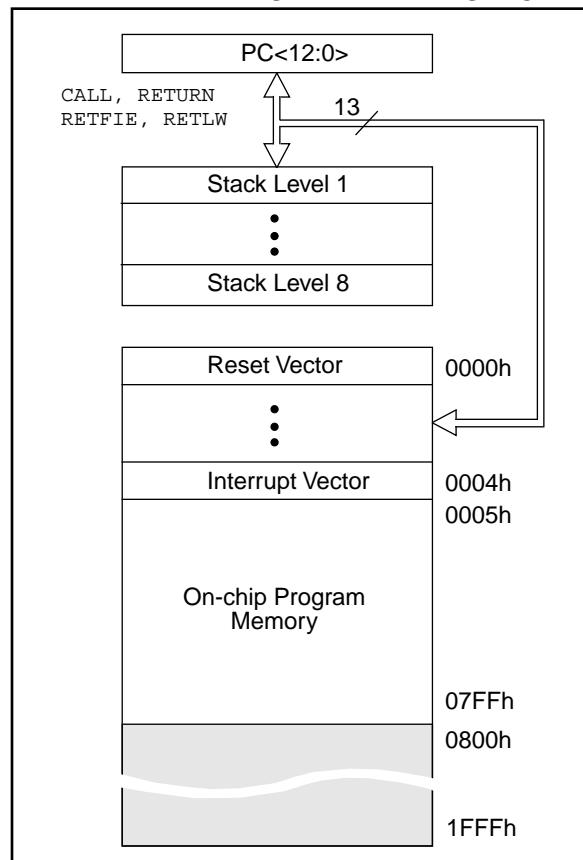


FIGURE 4-3: PIC16C715 PROGRAM MEMORY MAP AND STACK



PIC16C71X

4.2 Data Memory Organization

The data memory is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bit RP0 is the bank select bit.

RP0 (STATUS<5>) = 1 → Bank 1

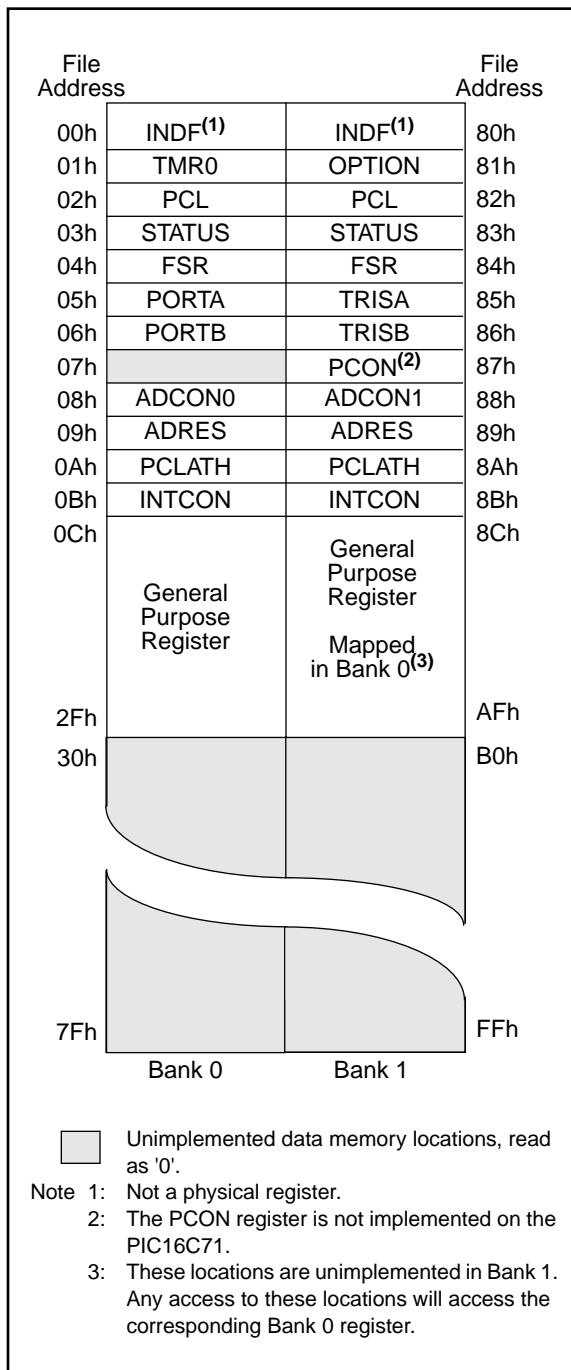
RP0 (STATUS<5>) = 0 → Bank 0

Each Bank extends up to 7Fh (128 bytes). The lower locations of each Bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers implemented as static RAM. Both Bank 0 and Bank 1 contain special function registers. Some "high use" special function registers from Bank 0 are mirrored in Bank 1 for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

FIGURE 4-4: PIC16C710/71 REGISTER FILE MAP



PIC16C71X

4.2.2.2 OPTION REGISTER

Applicable Devices	710	71	711	715
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The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the External INT Interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer by setting bit PSA (OPTION<3>).

FIGURE 4-8: OPTION REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBP _U	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **RBP_U**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

PIC16C71X

7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (R_s) and the internal sampling switch (R_{ss}) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (R_{ss}) impedance varies over the device voltage (V_{DD}), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current).

The maximum recommended impedance for analog sources is 10 k Ω . After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

EQUATION 7-1: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \cdot (1 - e^{(-TCAP/CHOLD(RIC + R_{SS} + R_s))})$$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$$TCAP = -(51.2 \text{ pF})(1 \text{ k}\Omega + R_{SS} + R_s) \ln(1/511)$$

Example 7-1 shows the calculation of the minimum required acquisition time T_{ACQ} . This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

$R_s = 10 \text{ k}\Omega$

1/2 LSb error

$V_{DD} = 5V \rightarrow R_{ss} = 7 \text{ k}\Omega$

Temp (application system max.) = 50°C

$V_{HOLD} = 0$ @ $t = 0$

Note 1: The reference voltage (V_{REF}) has no effect on the equation, since it cancels itself out.

Note 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

Note 3: The maximum recommended impedance for analog sources is 10 k Ω . This is required to meet the pin leakage specification.

Note 4: After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$T_{ACQ} = \text{Amplifier Settling Time} +$
Holding Capacitor Charging Time +
Temperature Coefficient

$$T_{ACQ} = 5 \mu s + TCAP + [(Temp - 25^\circ C)(0.05 \mu s/^\circ C)]$$

$$TCAP = -CHOLD (RIC + R_{SS} + R_s) \ln(1/511)$$

$$-51.2 \text{ pF} (1 \text{ k}\Omega + 7 \text{ k}\Omega + 10 \text{ k}\Omega) \ln(0.0020)$$

$$-51.2 \text{ pF} (18 \text{ k}\Omega) \ln(0.0020)$$

$$-0.921 \mu s (-6.2364)$$

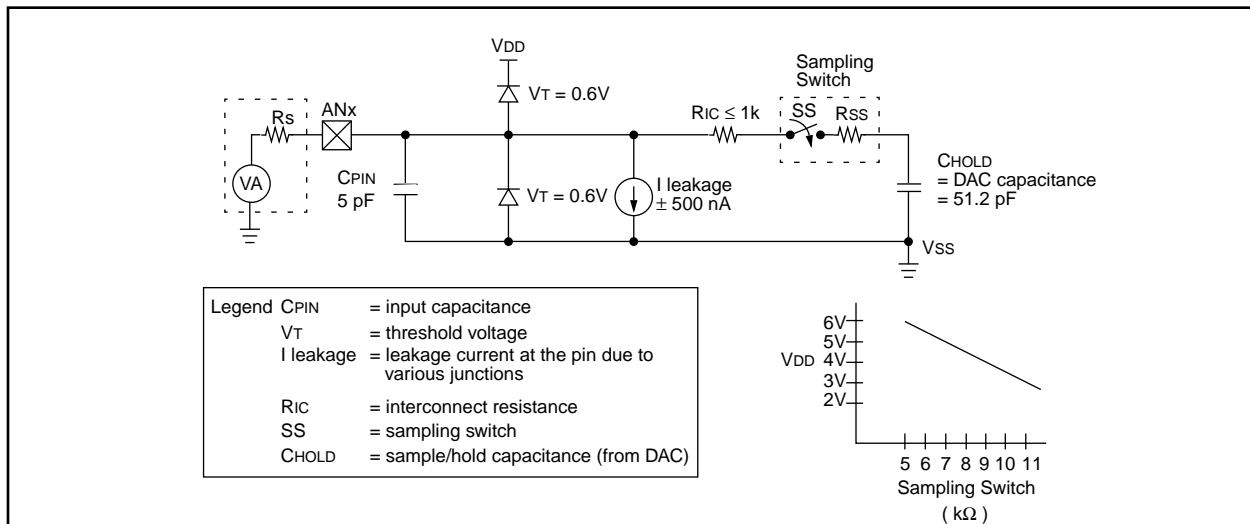
$$5.747 \mu s$$

$$T_{ACQ} = 5 \mu s + 5.747 \mu s + [(50^\circ C - 25^\circ C)(0.05 \mu s/^\circ C)]$$

$$10.747 \mu s + 1.25 \mu s$$

$$11.997 \mu s$$

FIGURE 7-5: ANALOG INPUT MODEL



PIC16C71X

TABLE 8-10: RESET CONDITION FOR SPECIAL REGISTERS, PIC16C710/711/711

Condition	Program Counter	STATUS Register	PCON Register PIC16C710/711
Power-on Reset	000h	0001 1xxx	---- --0x
MCLR Reset during normal operation	000h	000u uuuu	---- --uu
MCLR Reset during SLEEP	000h	0001 0uuu	---- --uu
WDT Reset	000h	0000 1uuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset (PIC16C710/711)	000h	0001 1uuu	---- --u0
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 8-11: RESET CONDITION FOR SPECIAL REGISTERS, PIC16C715

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	u--- -10x
MCLR Reset during normal operation	000h	000u uuuu	u--- -uuu
MCLR Reset during SLEEP	000h	0001 0uuu	u--- -uuu
WDT Reset	000h	0000 1uuu	u--- -uuu
WDT Wake-up	PC + 1	uuu0 0uuu	u--- -uuu
Brown-out Reset	000h	0001 1uuu	u--- -uu0
Parity Error Reset	000h	uuu1 0uuu	u--- -0uu
Interrupt wake-up from SLEEP	PC + 1 ⁽¹⁾	uuu1 0uuu	u--- -uuu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

TABLE 8-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS, PIC16C710/71/711

Register	Power-on Reset, Brown-out Reset ⁽⁵⁾	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	N/A	N/A	N/A
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000h	0000h	PC + 1 ⁽²⁾
STATUS	0001 1xxx	000q quuu ⁽³⁾	uuuq quuu ⁽³⁾
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	---x 0000	---u 0000	---u uuuu
PORTB	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	---0 0000	---0 0000	---u uuuu
INTCON	0000 000x	0000 000u	uuuu uuuu ⁽¹⁾
ADRES	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	00-0 0000	00-0 0000	uu-u uuuu
OPTION	1111 1111	1111 1111	uuuu uuuu
TRISA	---1 1111	---1 1111	---u uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
PCON ⁽⁴⁾	---- --0u	---- --uu	---- --uu
ADCON1	---- --00	---- --00	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 8-10 for reset value for specific condition.

4: The PCON register is not implemented on the PIC16C71.

5: Brown-out reset is not implemented on the PIC16C71.

FIGURE 8-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 1

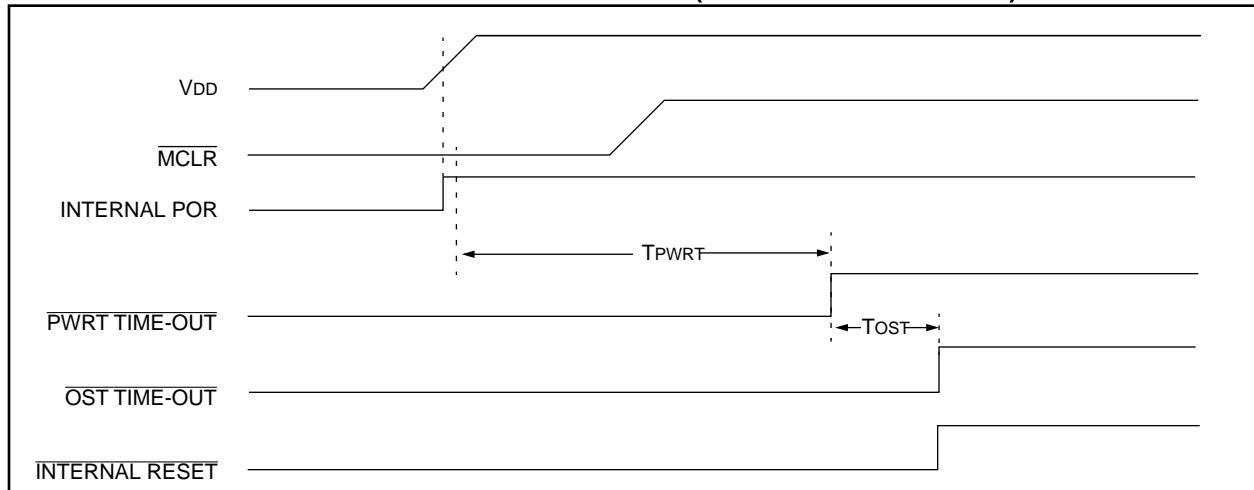


FIGURE 8-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 2

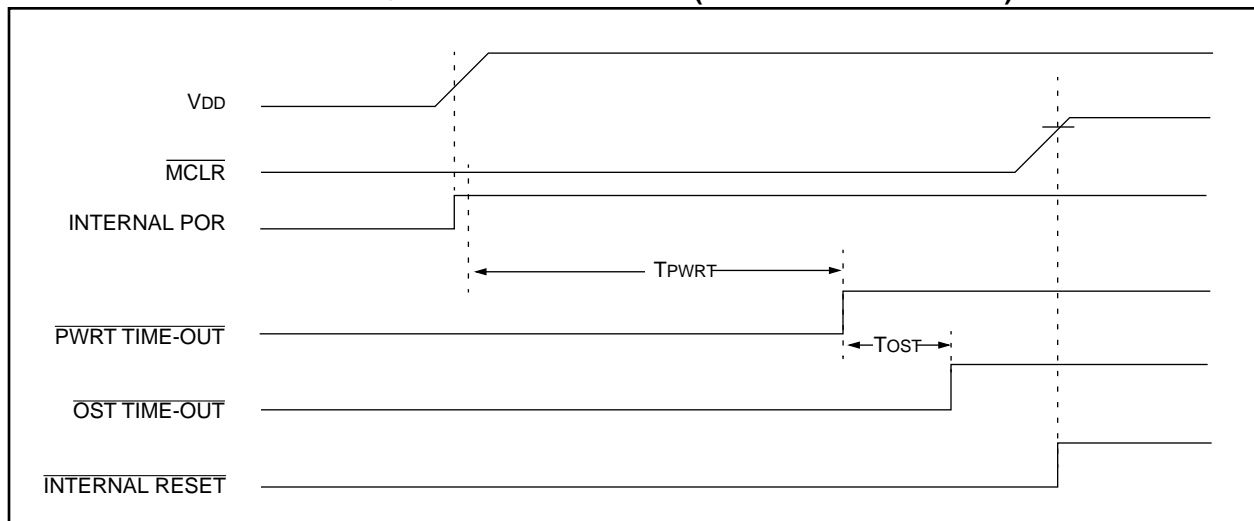


FIGURE 8-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})

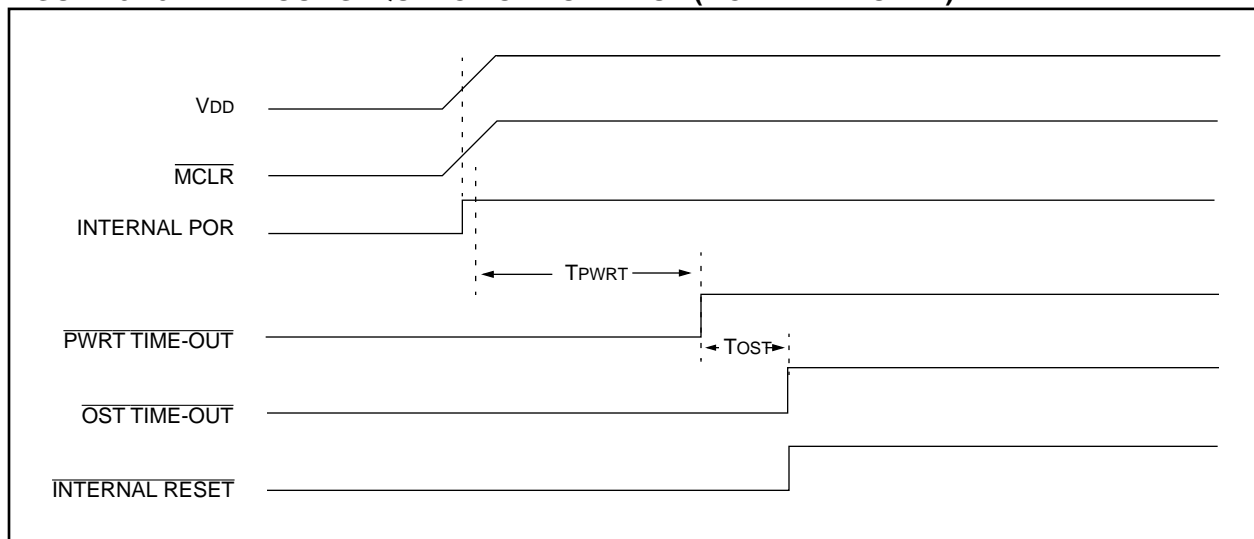
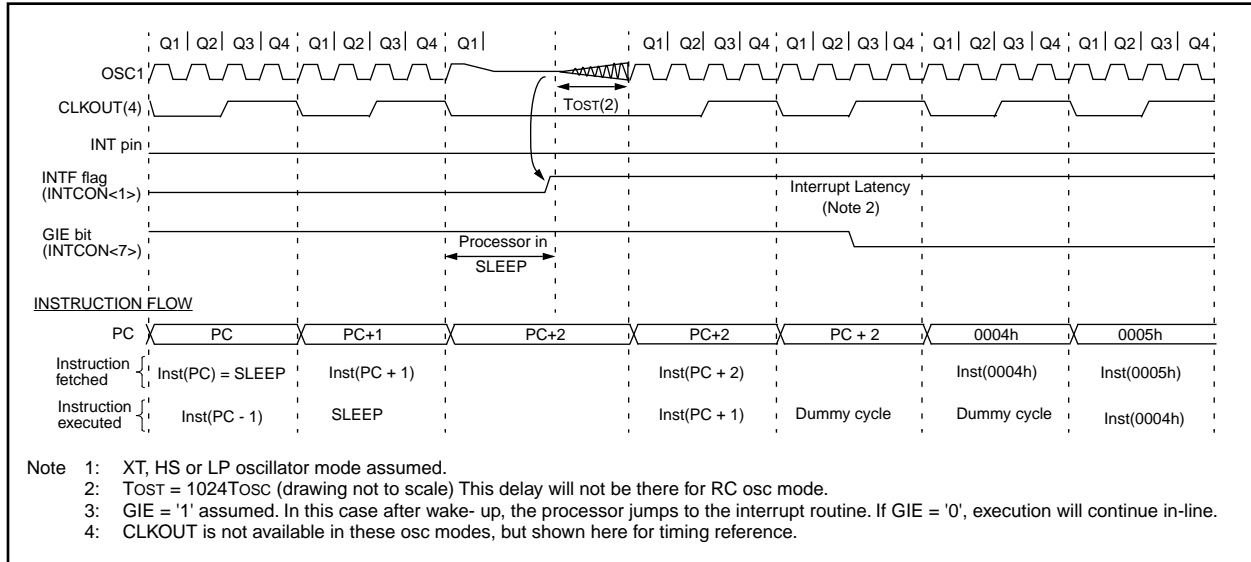


FIGURE 8-22: WAKE-UP FROM SLEEP THROUGH INTERRUPT



8.9 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

8.10 ID Locations

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

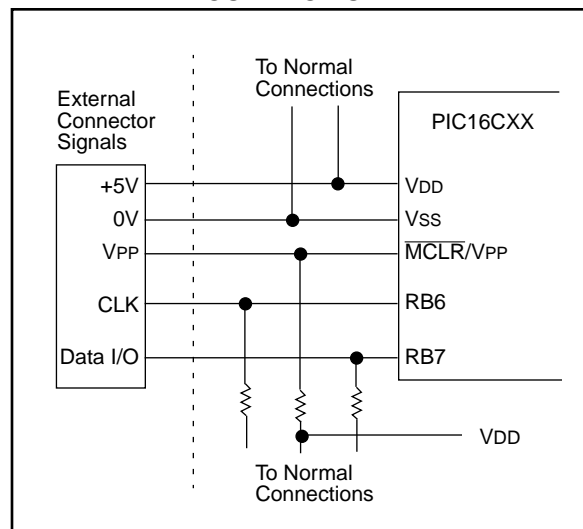
8.11 In-Circuit Serial Programming

PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the RB6 and RB7 pins low while raising the MCLR (VPP) pin from V_{IL} to V_{IH} (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

FIGURE 8-23: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



PIC16C71X

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → \overline{TO} ,
0 → \overline{PD}

Status Affected: \overline{TO} , \overline{PD}

Encoding:

00	0000	0110	0011
----	------	------	------

Description: The power-down status bit, \overline{PD} is cleared. Time-out status bit, \overline{TO} is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See Section 8.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	NOP	NOP	Go to Sleep

Example: SLEEP

SUBLW

Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: $0 \leq k \leq 255$

Operation: $k - (W) \rightarrow (W)$

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk
----	------	------	------

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1: SUBLW 0x02

Before Instruction

W = 1
C = ?
Z = ?

After Instruction

W = 1
C = 1; result is positive
Z = 0

Example 2: Before Instruction

W = 2
C = ?
Z = ?

After Instruction

W = 0
C = 1; result is zero
Z = 1

Example 3: Before Instruction

W = 3
C = ?
Z = ?

After Instruction

W = 0xFF
C = 0; result is negative
Z = 0

PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 11-7: A/D CONVERSION TIMING

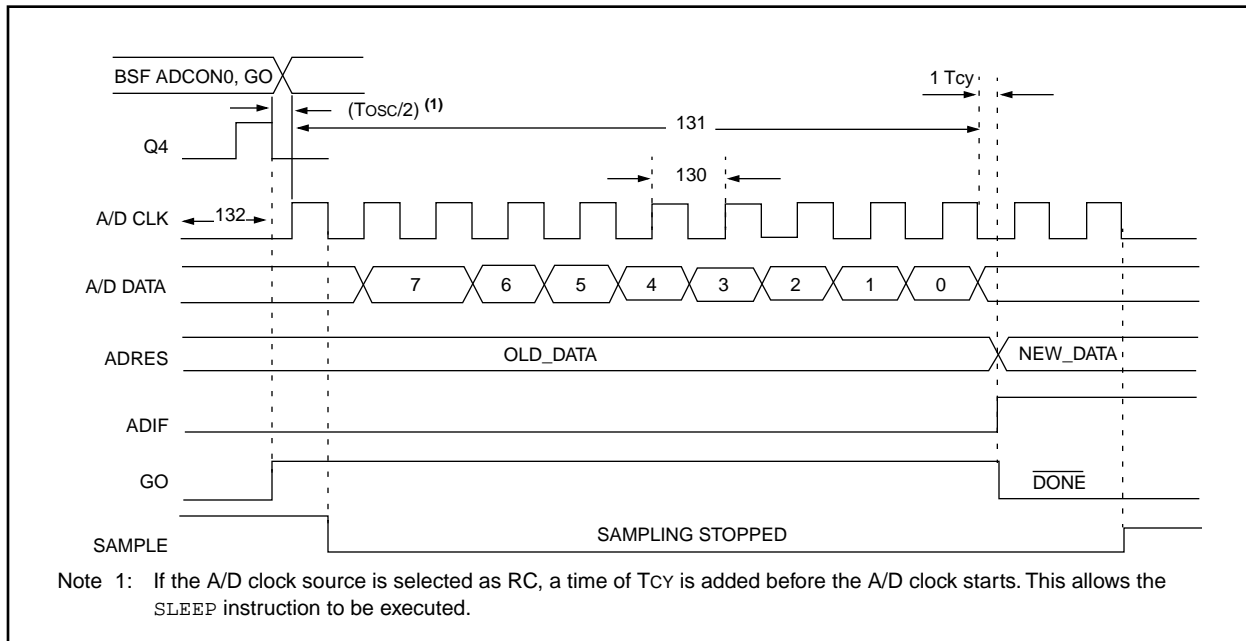


TABLE 11-7: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16C710/711	1.6	—	—	μs TOSC based, $V_{REF} \geq 3.0V$
			PIC16LC710/711	2.0	—	—	μs TOSC based, V_{REF} full range
			PIC16C710/711	2.0*	4.0	6.0	μs A/D RC mode
			PIC16LC710/711	3.0*	6.0	9.0	μs A/D RC mode
131	TCNV	Conversion time (not including S/H time). (Note 1)	—	9.5	—	TAD	
132	TACQ	Acquisition time	Note 2	20	—	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 19.5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
			5*	—	—	μs	
134	TGO	Q4 to AD clock start	—	$T_{OSC}/2§$	—	—	If the A/D clock source is selected as RC, a time of T_{CY} is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	Tswc	Switching from convert → sample time	1.5§	—	—	TAD	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Note 1: **ADRES** register may be read on the following T_{CY} cycle.

2: See Section 7.1 for min conditions.

FIGURE 12-25: TYPICAL I_{DD} vs. FREQUENCY
(LP MODE, 25°C)

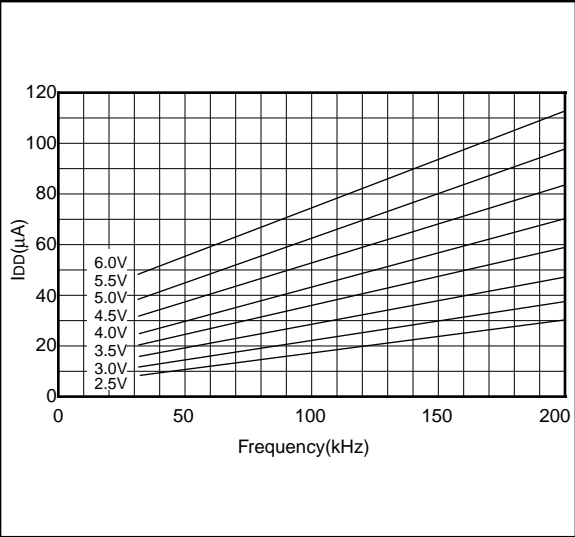


FIGURE 12-27: TYPICAL I_{DD} vs. FREQUENCY
(XT MODE, 25°C)

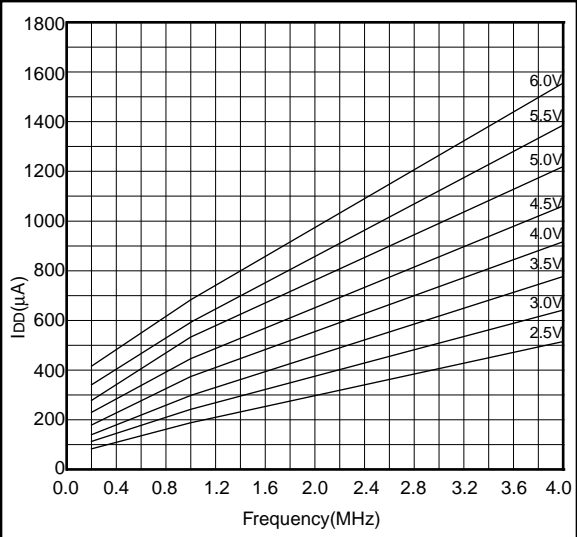


FIGURE 12-26: MAXIMUM I_{DD} vs.
FREQUENCY
(LP MODE, 85°C TO -40°C)

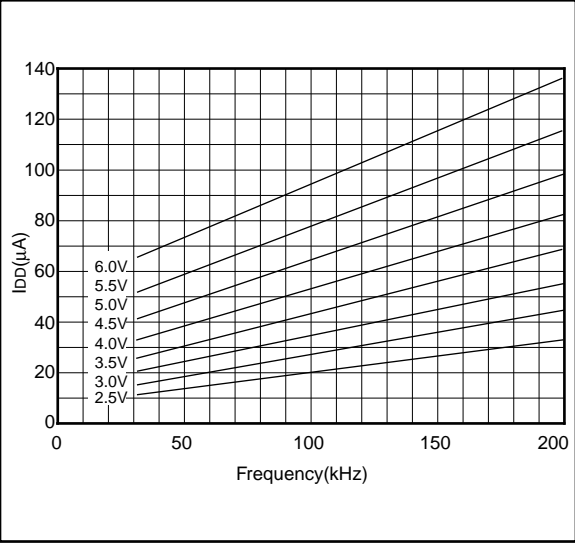
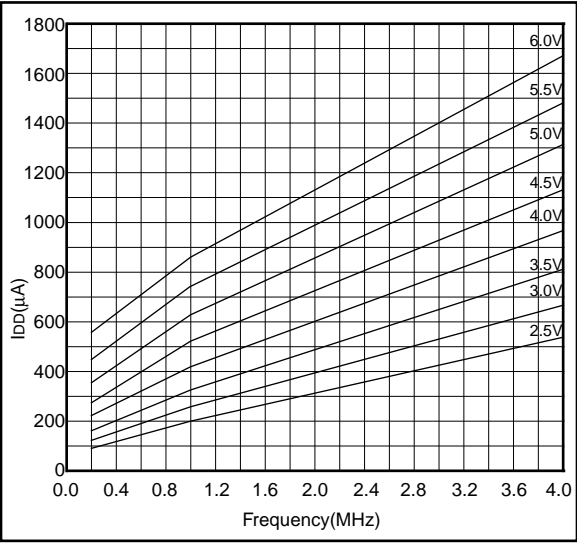


FIGURE 12-28: MAXIMUM I_{DD} vs.
FREQUENCY
(XT MODE, -40°C TO 85°C)



PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 12-29: TYPICAL I_{DD} vs. FREQUENCY
(HS MODE, 25°C)

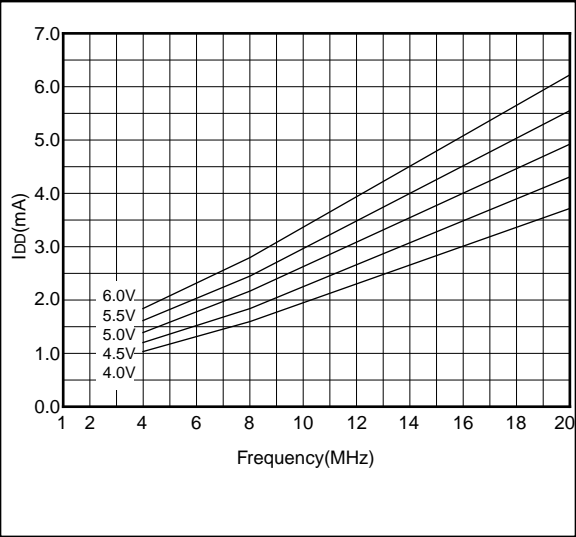
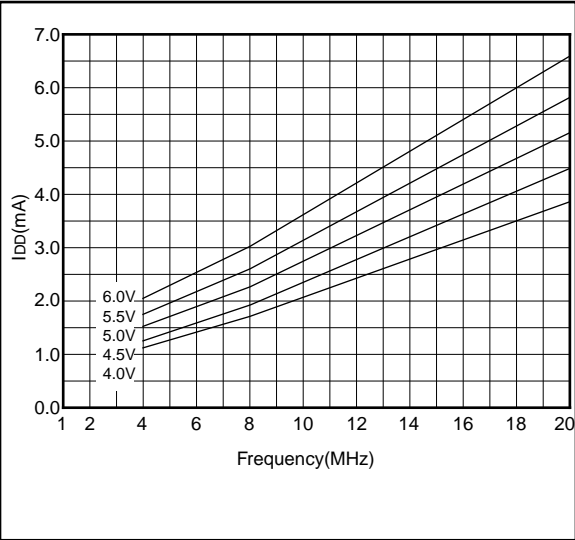


FIGURE 12-30: MAXIMUM I_{DD} vs. FREQUENCY
(HS MODE, -40°C TO 85°C)



13.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

- 1. TppS2ppS
- 2. TppS

T		T	
F	Frequency	T	Time

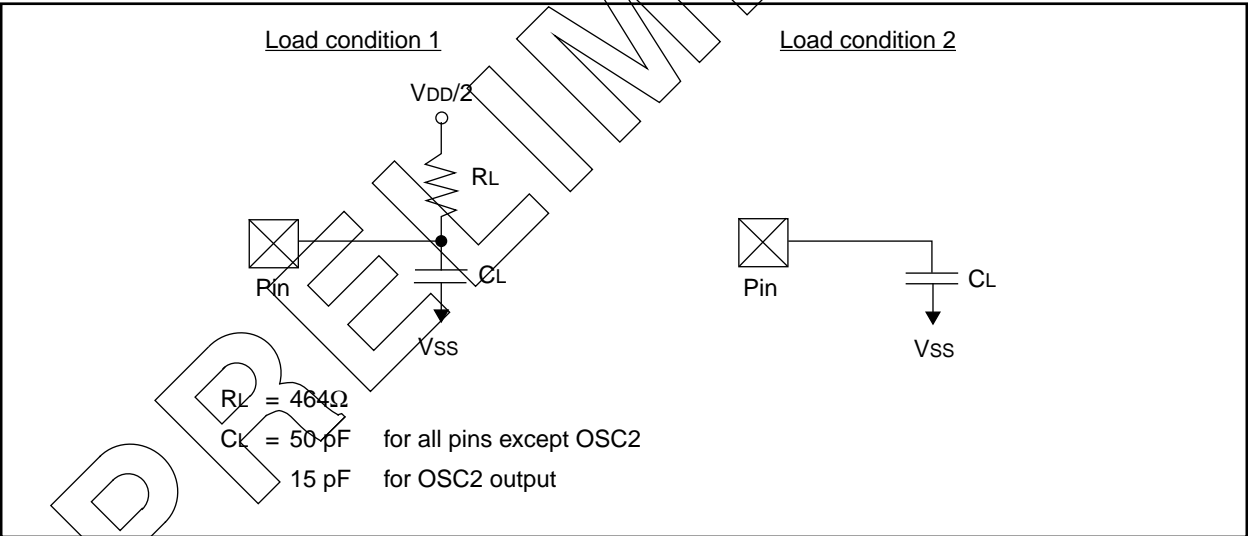
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
cs	CS	rw	RD or WR
di	SDI	sc	SCK
do	SDO	ss	SS
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

FIGURE 13-1: LOAD CONDITIONS



14.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C715

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified V_{DD} range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C, while 'max' or 'min' represents (mean +3 σ) and (mean -3 σ) respectively where σ is standard deviation.

FIGURE 14-1: TYPICAL I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)

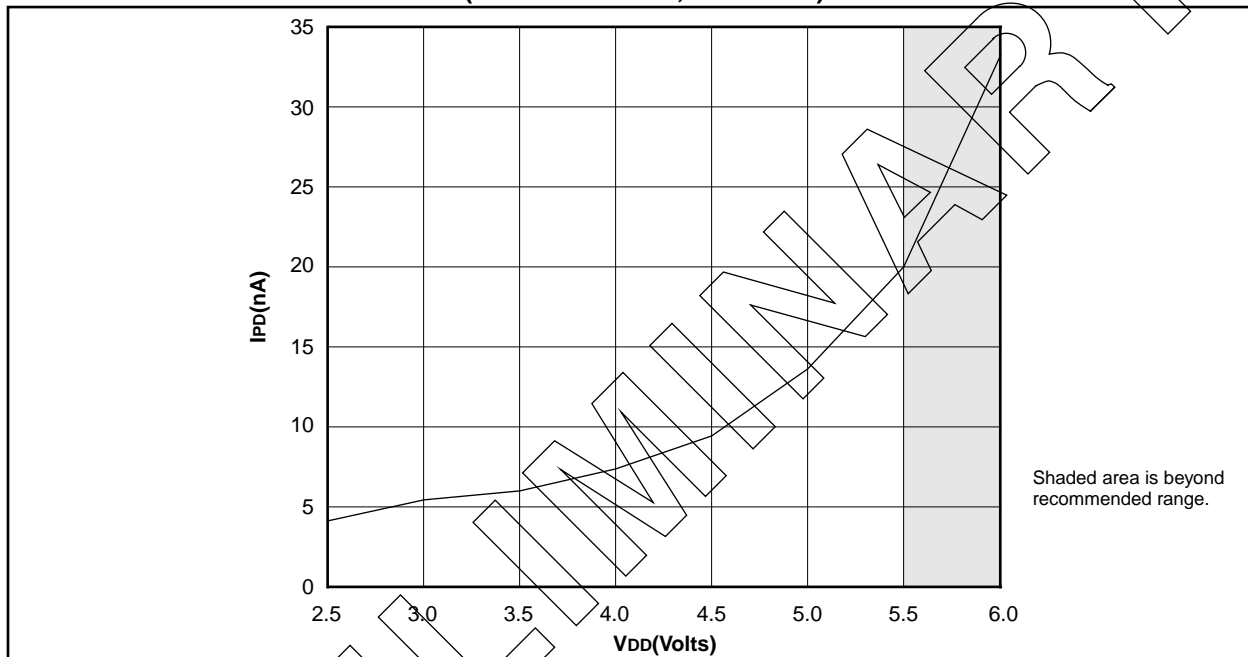
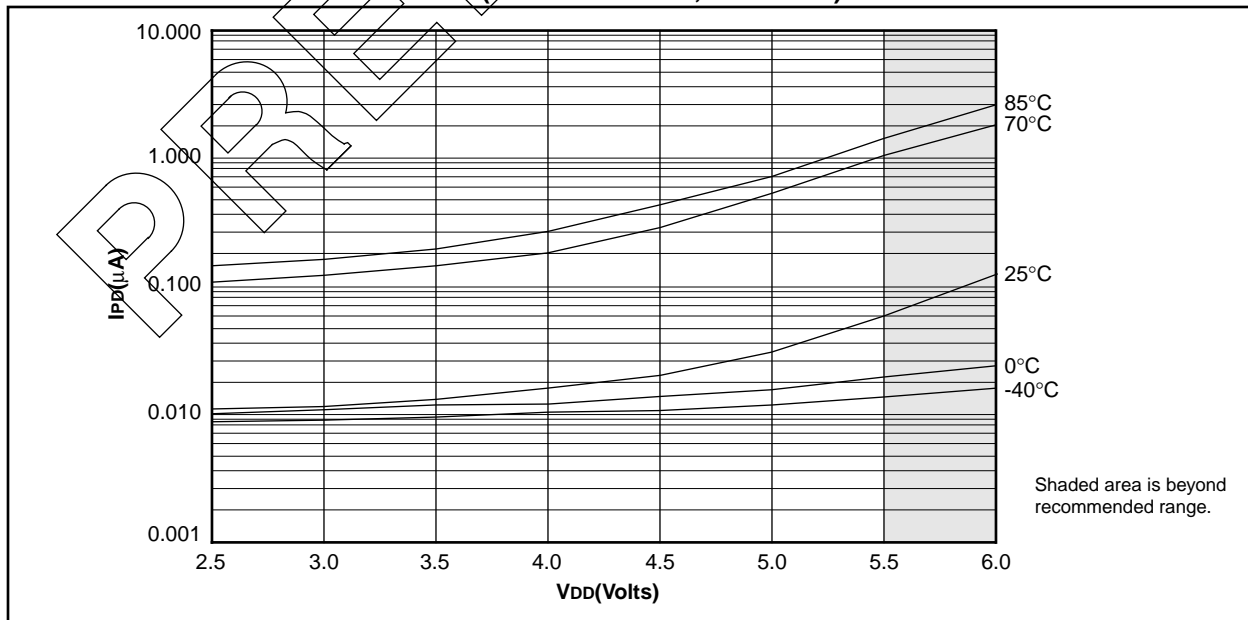


FIGURE 14-2: MAXIMUM I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)



15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C71

Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$, and RA4).....	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2).....	0 to +14V
Voltage on RA4 with respect to VSS	0 to +14V
Total power dissipation (Note 1).....	800 mW
Maximum current out of VSS pin	150 mA
Maximum current into VDD pin	100 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > VDD).....	± 20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > VDD)	± 20 mA
Maximum output current sunk by any I/O pin.....	25 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA	80 mA
Maximum current sourced by PORTA	50 mA
Maximum current sunk by PORTB.....	150 mA
Maximum current sourced by PORTB.....	100 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times (I_{DD} - \sum I_{OH}) + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

Note 2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C71-04	PIC16C71-20	PIC16LC71-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 15 μA typ. at 32 kHz, 4.0V IPD: 0.6 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

FIGURE 16-12: TYPICAL I_{DD} vs. FREQ (EXT CLOCK, 25°C)

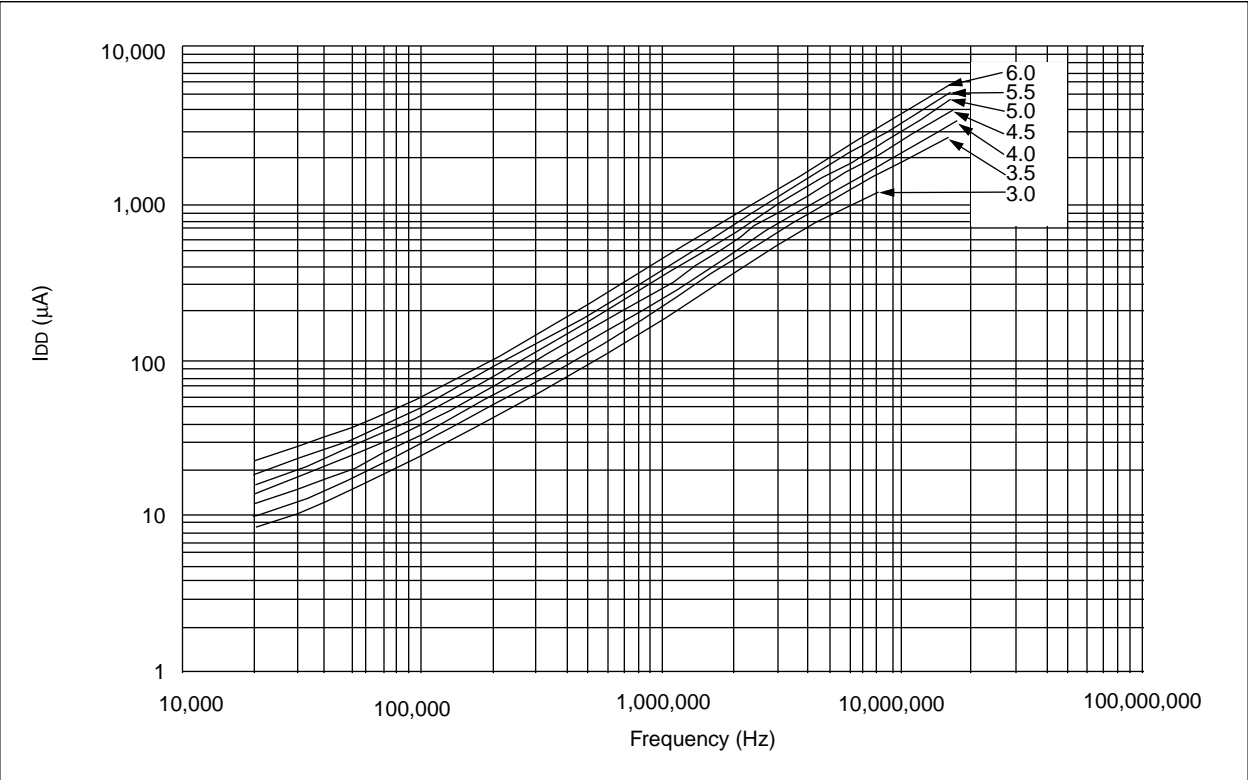
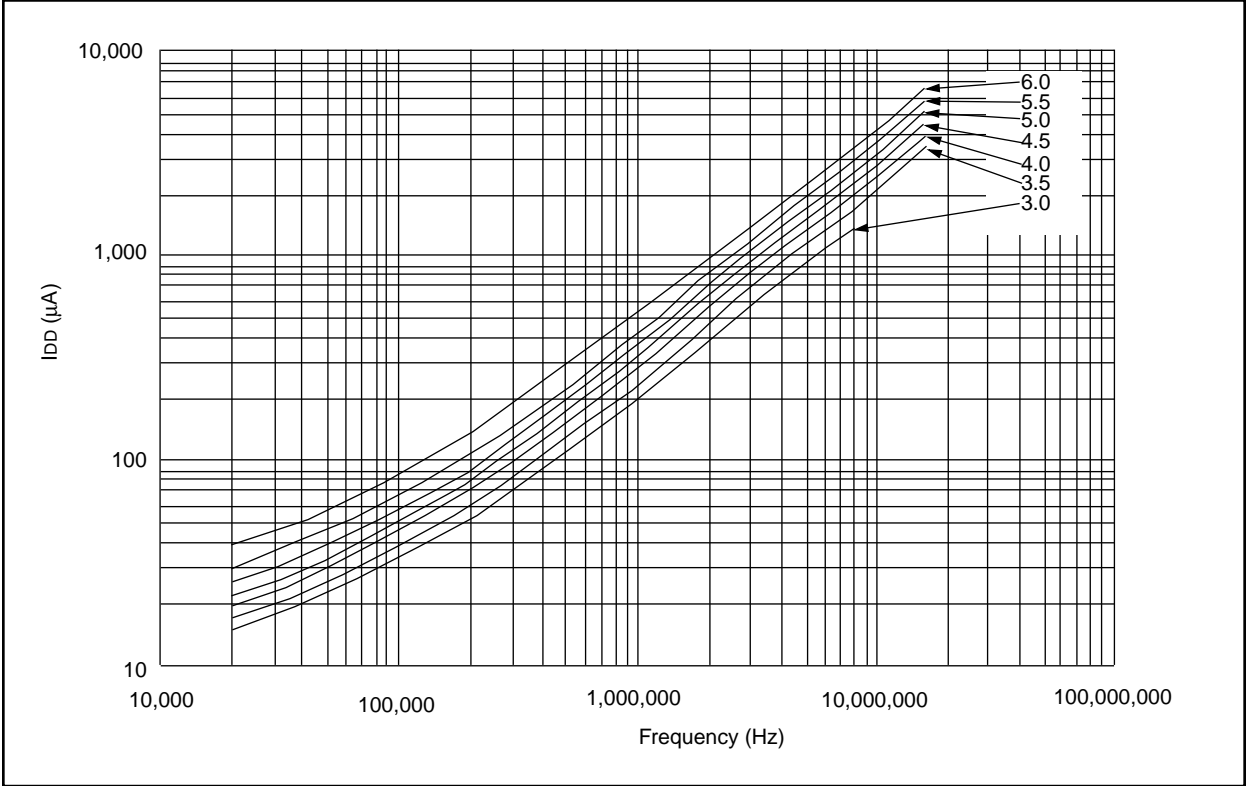


FIGURE 16-13: MAXIMUM, I_{DD} vs. FREQ (EXT CLOCK, -40° TO +85°C)



Data based on matrix samples. See first page of this section for details.

FIGURE 16-17: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

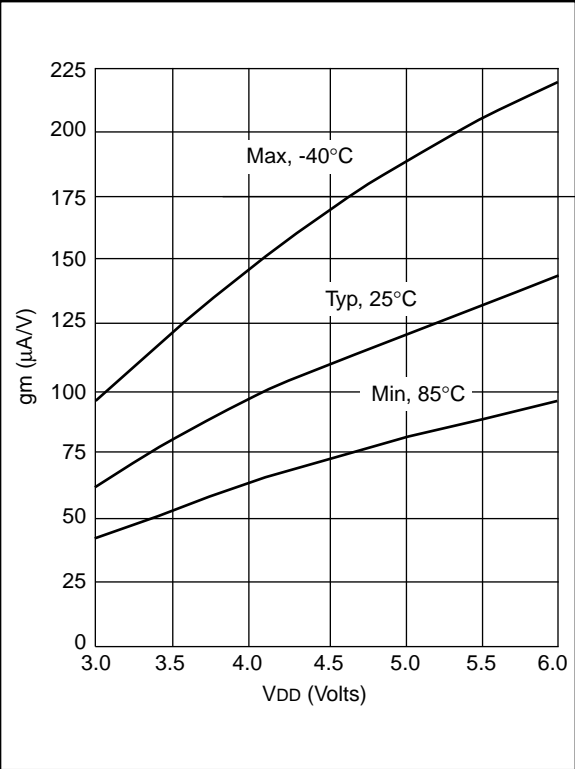


FIGURE 16-19: I_{OH} vs. V_{OH}, VDD = 3V

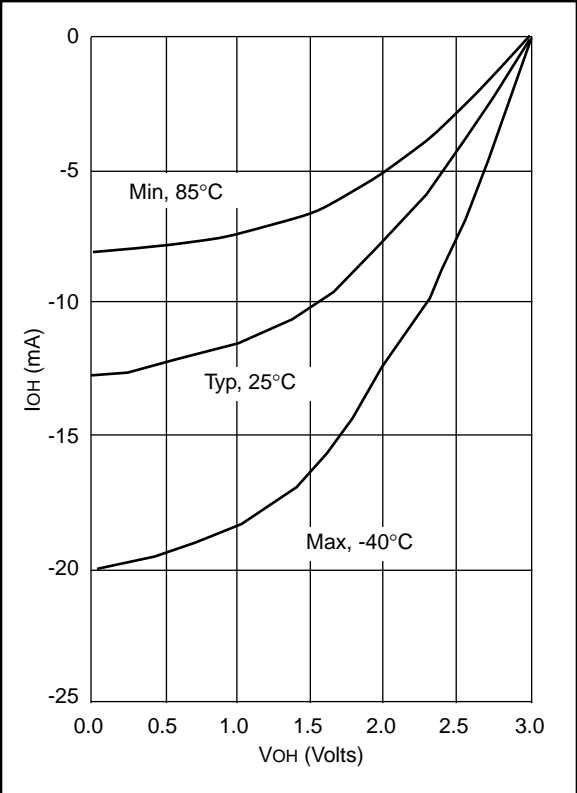


FIGURE 16-18: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD

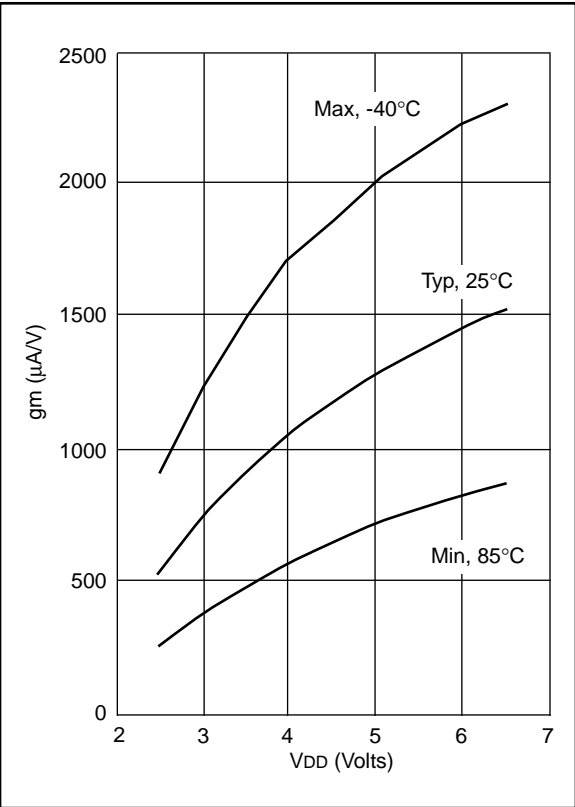
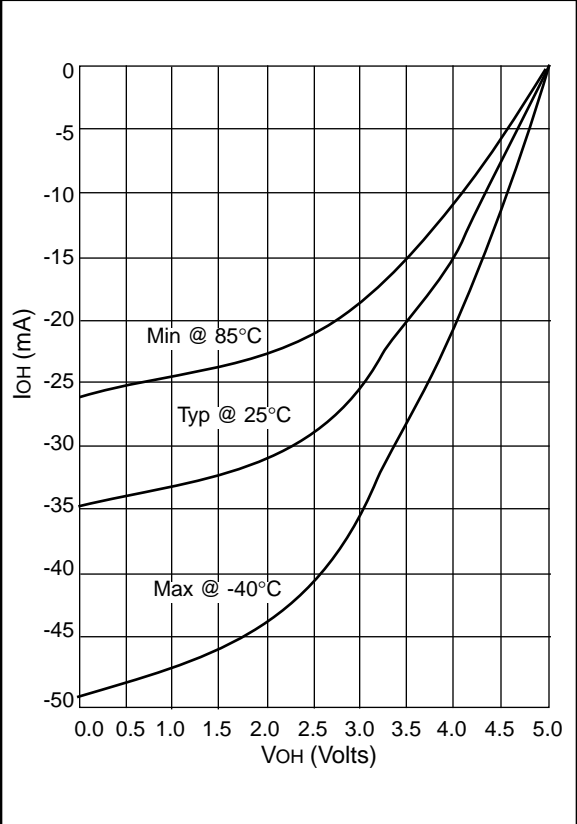


FIGURE 16-20: I_{OH} vs. V_{OH}, VDD = 5V



Data based on matrix samples. See first page of this section for details.

APPENDIX A:

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (1K now as opposed to 512 before) and register file (68 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake up from SLEEP through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight bit register.
15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, $\overline{\text{MCLR}}$ /VPP, RB6 (clock) and RB7 (data in/out).
16. PCON status register is added with a Power-on Reset status bit (POR).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by configuration word bit BODEN. Brown-out reset ensures the device is placed in a reset condition if VDD dips below a fixed set-point.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change reset vector to 0000h.

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3. Depress the **<Enter>** key and a garbage string will appear because CompuServe is expecting a 7E1 setting.
4. Type +, depress the **<Enter>** key and "Host Name:" will appear.
5. Type MCHIPBBS, depress the **<Enter>** key and you will be connected to the Microchip BBS.

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